

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions and listings of the claims in this application.

LISTING OF CLAIMS:

1. (Currently Amended) Apparatus for supporting, during a testing operation, a leadframe formed with at least one row of non-singulated semiconductor devices, comprising a main body and a leadframe support member, the leadframe support member being connected to the main body; wherein said leadframe support member is formed with at least one groove for receiving said semiconductor devices such that, during the testing operation, test probes from a test probe head are electrically connected with leads extending from said semiconductor devices, the leads ~~[[rest]]~~ resting upon a surface of said support member.

2. (Original) Apparatus as claimed in claim 1 wherein said leadframe support member is formed with a plurality of parallel grooves.

3. (Original) Apparatus as claimed in claim 1 further comprising means for releasably gripping a said leadframe so as to hold said leadframe in place.

4. (Original) Apparatus as claimed in claim 3 wherein said gripping means comprises a pair of gripping members disposed on respective sides of said groove.

5. (Previously Presented) Apparatus as claimed in claim 4 wherein means are provided for moving said gripping members into and out of engagement with said leadframe.

6. (Previously Presented) Apparatus as claimed in claim 5 wherein said moving means is actuated by compressed air.

7. (Original) Apparatus as claimed in claim 6 wherein a plurality of pairs of gripping members are provided, and wherein said compressed air is provided directly to one said pair and is distributed to the other said pairs by an air distribution assembly formed in the main body.

8. (Original) Apparatus as claimed in claim 3 wherein said gripping means extends through apertures formed in said leadframe support member.

9. (Original) Apparatus as claimed in claim 1 wherein said main body is formed with locating pins for locating the leadframe support member on the main body.

10. (Currently Amended) Apparatus as claimed in claim 1 wherein said main body is formed of a conducting material and ~~an electrical grounding is provided at holes located on the main body~~ includes holes for providing an electrical grounding.

11. (Original) Apparatus as claimed in claim 1 wherein the leadframe support member is formed of a high resistivity electrically insulating material.

12. (Original) Apparatus as claimed in claim 1 wherein said main body is provided with identification means.

13. (Currently Amended) Apparatus for supporting during a testing operation a leadframe formed with at least one row of non-singulated semiconductor devices, comprising a main body, a leadframe support member, the leadframe support member being connected to the main body, wherein said leadframe support member is formed with at least one groove for receiving said semiconductor devices such that in use, test probes from a test probe head are electrically connected with leads extending from said semiconductor devices, the leads lying [[lie]] on a surface of said support member, and means for coupling said main body with a transport mechanism.

14. (Previously Presented) Apparatus as claimed in claim 1, wherein each groove receives a plurality of semiconductor devices.

15. (Previously Presented) Apparatus as claimed in claim 2, wherein each groove receives a plurality of semiconductor devices.

16. (New) Apparatus as claimed in claim 1, wherein the main body member includes a recess and the leadframe support member is located in the recess.

17. (New) Apparatus as claimed in claim 13 wherein the means for coupling include a coupler rod having two ends, each end of the connector rod is coupled to a coupling block, and each coupling block is secured to the main body.